

2020년 2월 13일(목), 10:45~12:30

Room I (하트 II, 6층)

A. Interconnect & Package 분과
[TI2-A] Interconnect & Packaging

TI2-A-1 10:45~11:15	[초청] TBA 이후정 성균관대학교
TI2-A-2 11:15~11:45	[초청] Thermo-Mechanical Reliability and Properties Evaluation for Advanced Electronic Packages Tae-Ik Lee KITECH
TI2-A-3 11:45~12:00	Laser-Assisted Bonding (LAB) – Versatile Enabling Technology for the 4th Industrial Revolutions Kwang-Seong Choi, Jiho Joo, Ki-seok Jang, Gwang-Mun Choi, Ho-Gyeong Yun, Seok Hwan Moon, and Yong-Sung Eom ICT Creative Laboratory, ETRI
TI2-A-4 12:00~12:15	Spin-Related Resistances in Ferromagnetic/Nikelate Bilayers Se Yeob Jeong ¹ , Jongmin Lee ² , Nyun Jong Lee ¹ , Sanghan Lee ² , Tae Heon Kim ¹ , and Sanghoon Kim ¹ ¹ Department of Physics, University of Ulsan, ² School of Materials Science & Engineering, GIST
TI2-A-5 12:15~12:30	Density Functional Theory Study on the Atomic Layer Deposition of Tungsten by Using Tungsten Chloride Yewon Kim ¹ , Romel Hidayat ¹ , Soo-Hyun Kim ² , and Won-Jun Lee ¹ ¹ Department of Nanotechnology and Advanced Materials Engineering, Sejong University, ² School of Materials Science and Engineering, Yeungnam University